

Features

- Low power loss
- Super-fast recovery time for high efficiency
- Glass passivated chip junction
- Low leakage current
- High forward surge capability
- Solder dip maximum peak of 275 °C /7s, per JESD 22-B106
- AEC-Q101 qualified available
- Automotive product No.: base P/N-H



Typical Application

For use in high frequency rectification and freewheeling application in switching mode converters and inverters for consumer ,computer and telecommunication.



Mechanical Data

- Package: DO-204AC(DO-15)
Molding compound meets UL 94 V-0 flammability rating,RoHS-compliant
- Terminals:Tin plated leads, solderable per J-STD-002 and JESD22-B102
- Polarity: Color band denotes cathode end

Maximum Ratings (Ta=25°C Unless otherwise specified)

PARAMETER	Symbol	Unit	Conditions	SF2							
				1G	2G	3G	4G	5G	6G	7G	8G
Repetitive Peak Reverse Voltage	V_{RRM}	V		50	100	150	200	300	400	500	600
Average Forward Current	$I_{F(AV)}$	A		2.0							
Surge(Nonrepetitive)Forward Current	I_{FSM}	A	60HZ sine wave, 1 cycle, Ta=25°C	50							
Storage Temperature	T_{stg}	°C		-55 ~ +150							
Junction Temperature	T_j	°C		-55 ~ +150							

Electrical Characteristics (Ta=25°C Unless otherwise specified)

PARAMETER	Symbol	Unit	Conditions	SF2							
				1G	2G	3G	4G	5G	6G	7G	8G
Peak Forward Voltage	V_{FM}	V	$I_{FM} = 2.0A$	0.95			1.3		1.7		
Peak Reverse Current	I_{RRM1}	μA	$V_{RM} = V_{RRM}$	$T_a = 25^\circ C$			5				
	I_{RRM2}			$T_a = 125^\circ C$			150				
Maximum reverse recovery time	T_{rr}	ns	$I_F = 0.5A, I_R = 1.0A, I_{rr} = 0.25A$	35							
Thermal Resistance(Typical)	$R_{\theta J-A}$	°C/W	Between junction and ambient	40							
Typical junction capacitance	C_j	pF	Measured at 1MHZ and Applied Reverse Voltage of 4.0 V.D.C	50				30			

Characteristics (Typical)

FIG1: Forward Current Derating Curve

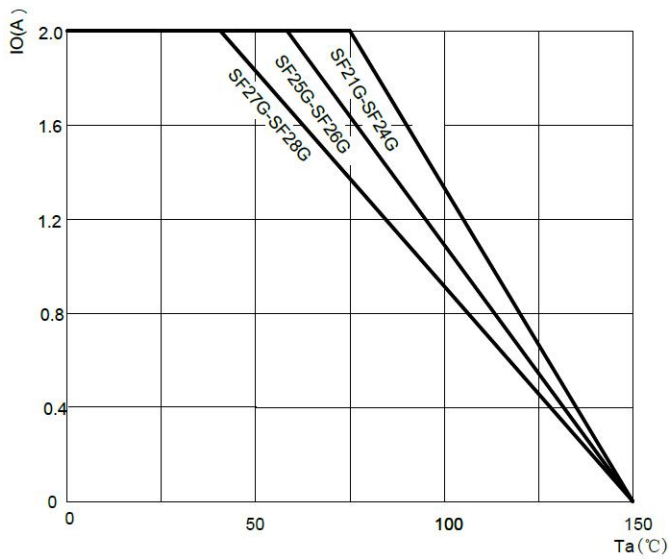


FIG2: Surge Forward Current Capability

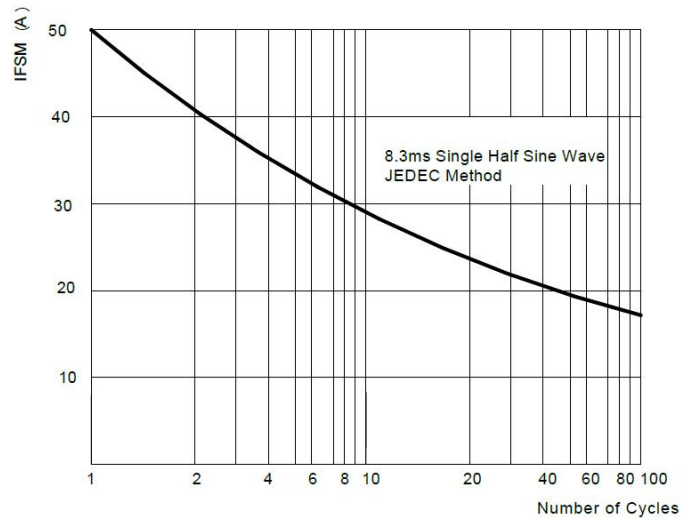


FIG3: Instantaneous Forward Voltage

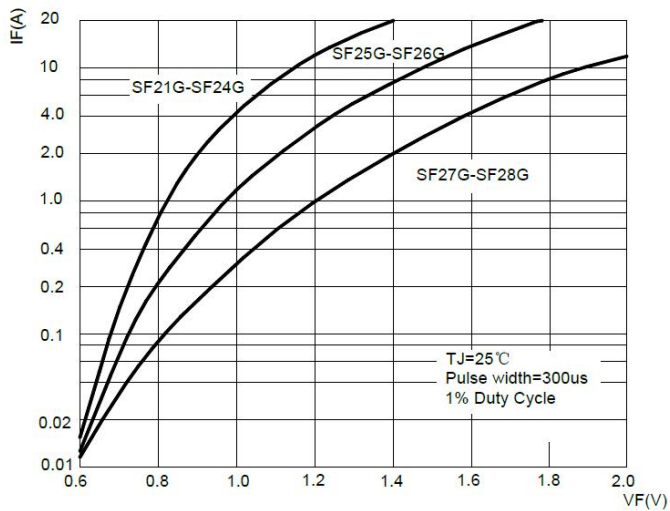


FIG4: Typical Reverse Characteristics

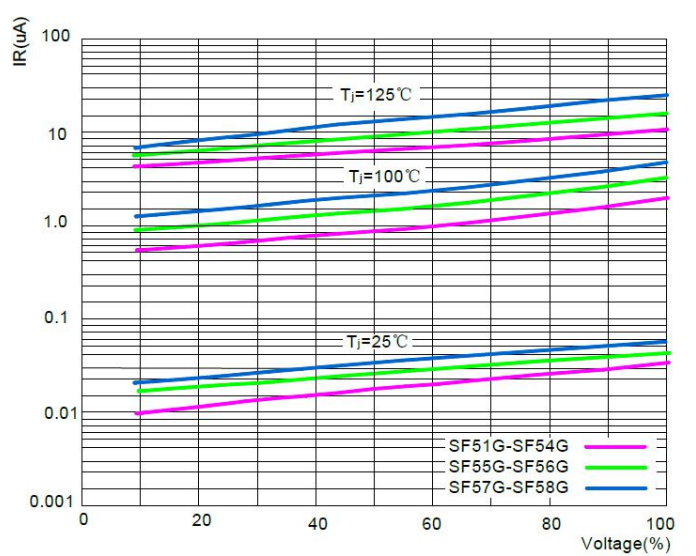
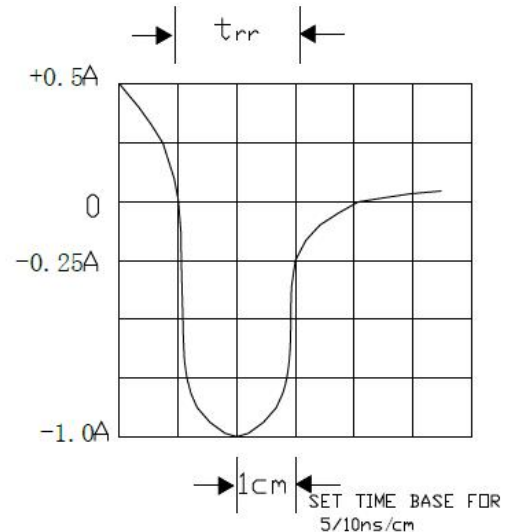
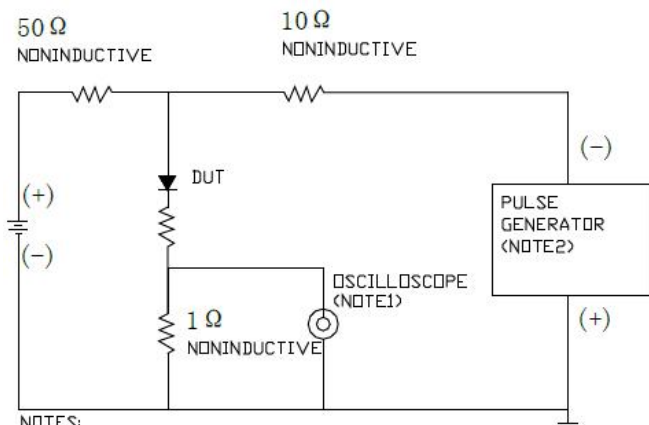


FIG5: Diagram of circuit and Testing wave form of reverse recovery time



NOTES:
1. Rise Time = 7ns max. Input Impedance = 1MΩ 22pf
2. Rise Time = 10ns max. Source Impedance = 50Ω



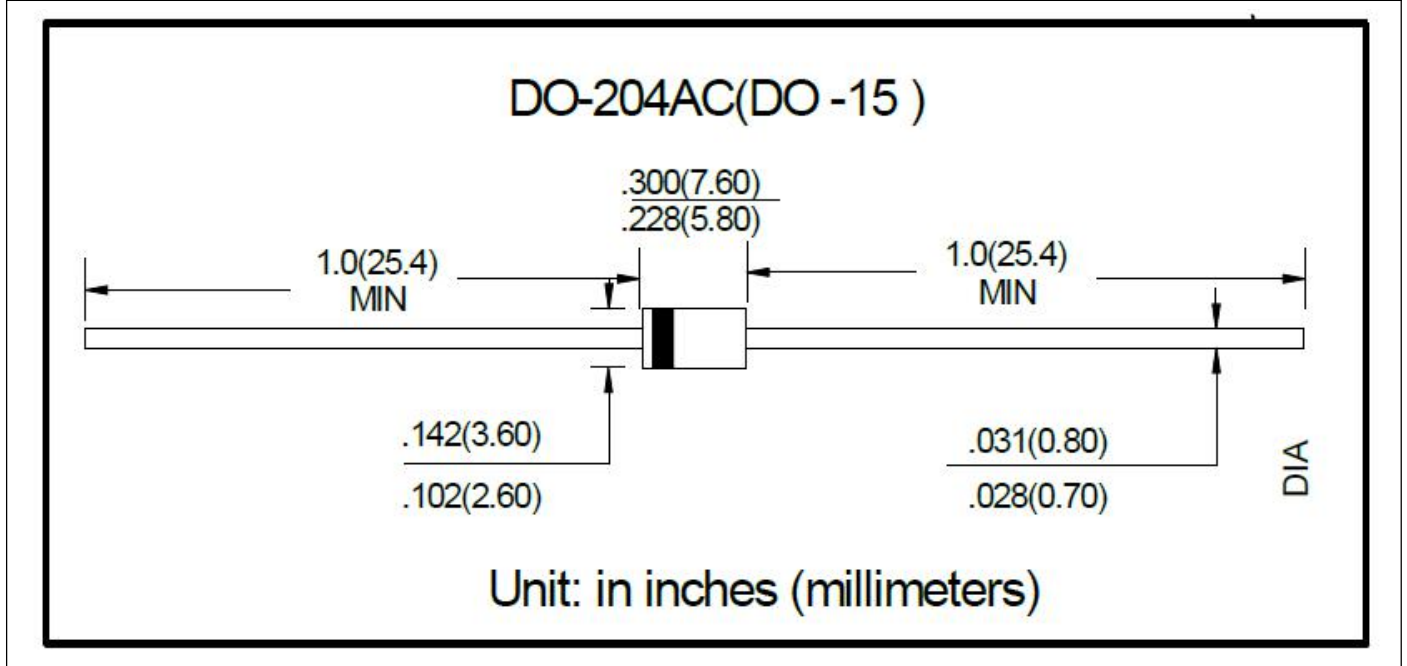
安美半导体
ANMEI Semiconductor

SF21G THRU SF28G

Ordering Information (Example)

PREFERED	PACKAGE CODE	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
SF21G~SF28G	DO-204AC(DO-15)	3000	3000	30000	Tape

Outline Dimensions



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